

MICROETCHING SOLUTION FOR COPPER, REPLENISHMENT SOLUTION THEREFOR AND METHOD FOR PRODUCTION OF WIRING BOARD

ABSTRACT

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Disclosed is a microetching solution, a replenishment solution added to said microetching solution and a method for production of a wiring board using said microetching solution. The microetching solution for copper consists of an aqueous solution containing a cupric ion, an organic acid, a halide ion, a polymer and a nonionic
10 surfactant. The polymer is a water-soluble polymer including a polyamine chain and/or a cationic group and having a weight average molecular weight of 1000 or more. In the microetching solution of the present invention, a value of A/B is 2000 to 9000 and a value of A/D is 500 to 9000, where a concentration of the halide ion is A% by weight, a concentration of the polymer is B% by weight and a concentration of the nonionic
15 surfactant is D% by weight. Using this microetching solution, adhesion to a resin or the like can be uniformly maintained even with a low etching amount.

[Fig. 2]